

Title (en)

METHOD AND APPARATUS FOR FORMING AN ADHESIVE SEALED PACKAGE

Publication

**EP 0179454 A3 19870805 (EN)**

Application

**EP 85113446 A 19851023**

Priority

US 66386684 A 19841023

Abstract (en)

[origin: EP0179454A2] A method and apparatus are provided for packaging products between first (26) and second plastic components sealed by using a hot melt adhesive applied by a dispensing applicator (40) in one of several serially arranged stations of a packaging operation. The first plastic component (26) is supported for indexing movement on a transport means (12) or is formed therein and moved under a hot melt applicator (40) which is continuously driven in a predetermined path of travel (50) which in part traverses the entire periphery of the product loaded first plastic component (26). The first plastic component (26) is stopped under the applicator (40) for a predetermined dwell time during which the applicator dispenses the hot melt adhesive, then advanced where the second plastic component is applied to form a filled package which is then evacuated and sealed. Apparatus is provided for preventing dripping or stringing of the hot melt adhesives.

IPC 1-7

**B65B 51/02**; **B65B 9/04**

IPC 8 full level

**B65B 9/04** (2006.01); **B65B 51/02** (2006.01)

CPC (source: EP)

**B65B 9/04** (2013.01); **B65B 51/023** (2013.01)

Citation (search report)

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**EP 0179454 A2 19860430**; **EP 0179454 A3 19870805**; CA 1267067 A 19900327; JP S62500581 A 19870312; WO 8602615 A1 19860509

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